

BR2N7002LK2Q

Rev.A Dec.-2023

描述 / Descriptions

SOT-23 塑封封装 N 沟道 MOS 场效应管。
N-CHANNEL MOSFET in a SOT-23 Plastic Package.

特征 / Features

灵敏的控制级触发电流和很低的维持电流。静电保护达 2KV，符合 AEC-Q101 标准高可靠性要求，无卤产品。

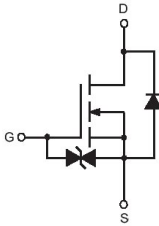
Sensitive gate trigger current and Low Holding current. ESD protected up to 2KV, Qualified to AEC-Q101 Standards for High Reliability, HF Product.

用途 / Applications

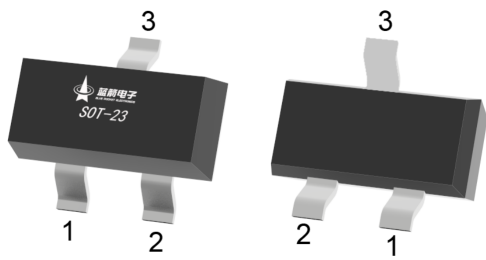
用作一般的开关和相位控制，满足汽车应用的严格要求。

Intended for use in general purpose switching and phase control applications, Meet the stringent requirements of automotive applications.

内部等效电路 / Equivalent Circuit



引脚排列 / Pinning



PIN1 : G

PIN 2 : S

PIN 3 : D

印章代码 / Marking

Marking	Q702LK
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极限参数 / Absolute Maximum Ratings(Ta=25°C)

参数 Parameter	符号 Symbol	数值 Rating	单位 Unit
Drain-Source Voltage	V _{DSS}	60	V
Drain Current - Continuous	I _D (Ta=25°C)	360	mA
	I _D (Ta=100°C)	230	
Drain Current - Pulsed(Note 1)	I _{DM}	1200	mA
Gate-Source Voltage - Continuous	V _{GSS}	±20	V
Power Dissipation	P _D	350	mW
Junction Temperature Range	T _j	150	°C
Storage Temperature Range	T _{stg}	-55~150	°C
Thermal resistance from junction to Ambient (Note 2)	R _{θJA}	300	°C/W
Thermal resistance from junction to solder point	R _{θJSP}	92	

Note 1) Pulse Width 10us, Duty Cycle 1%

Note 2) Surface-mounted on FR4 board using 1 sq in pad size with 1 oz Cu

电性能参数 / Electrical Characteristics(Ta=25°C)

参数 Parameter	符号 Symbol	测试条件 Test Conditions	最小值 Min	典型值 Typ	最大值 Max	单位 Unit
Drain-Source Breakdown Voltage	V _{DSS}	V _{GS} =0 I _D =250μA	60			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} =0 V _{DS} =60V			1.0	μA
Gate-Source Leakage current	I _{GSS}	V _{DS} =0V V _{GS} =±20V			±10	μA
Static Drain-Source On-Resistance	R _{DS(on)(1)}	V _{GS} =10V I _D =0.5A		1.1	1.44	Ω
	R _{DS(on)(2)}	V _{GS} =4.5V I _D =0.02A		1.2	2.25	
	R _{DS(on)(3)}	V _{GS} =2.5V I _D =0.1A		1.6	4.05	
	R _{DS(on)(4)}	V _{GS} =1.8V I _D =0.01A		2.7	6	
Drain-Source Diode Forward Voltage	V _{SD}	V _{GS} =0V I _S =500mA			1.2	V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} I _D =250μA	0.5	0.9	1.0	V
Input Capacitance	C _{iss}	V _{GS} =0V, f=1MHz, V _{DS} =20V		25	50	pF
Output Capacitance	C _{oss}			11	25	
Reverse Transfer Capacitance	C _{rss}			2.5	5	
Total Gate Charge	Q _{G(TOT)}	V _{GS} =4.5V, V _{DS} =10V; I _D =200 mA		0.7		nC
Threshold Gate Charge	Q _{G(TH)}			0.1		
Gate-to-Source Charge	Q _{GS}			0.3		
Gate-to-Drain Charge	Q _{GD}			0.1		

电性能参数 / Electrical Characteristics(Ta=25°C)

参数 Parameter	符号 Symbol	测试条件 Test Conditions	最小值 Min	典型值 Typ	最大值 Max	单位 Unit
Turn-On Delay Time	$t_{d(ON)}$	$V_{GS}=10V, V_{DD}=25V,$ $I_D=500mA, R_G=25\Omega$		12.2		ns
Rise Time	t_r			9.0		
Turn-Off Delay Time	$t_{d(OFF)}$			55.8		
Fall Time	t_f			29		

电参数曲线图 / Electrical Characteristic Curve

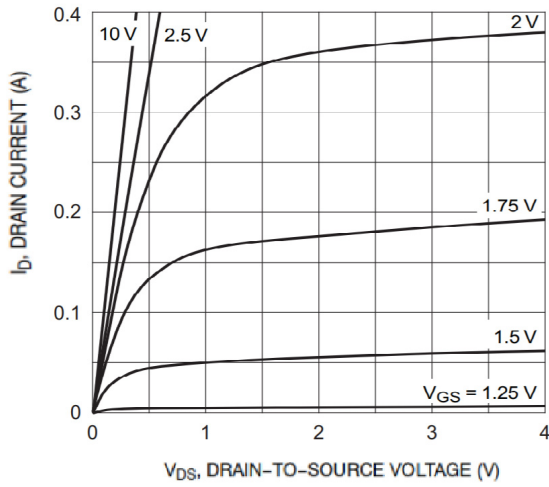


Figure 1. On-Region Characteristics

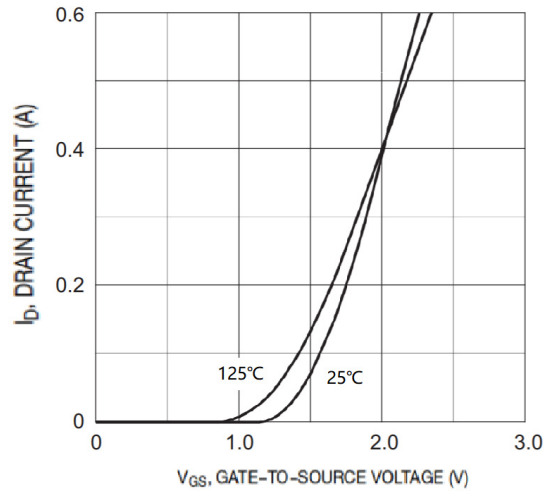


Figure 2. Transfer Characteristics

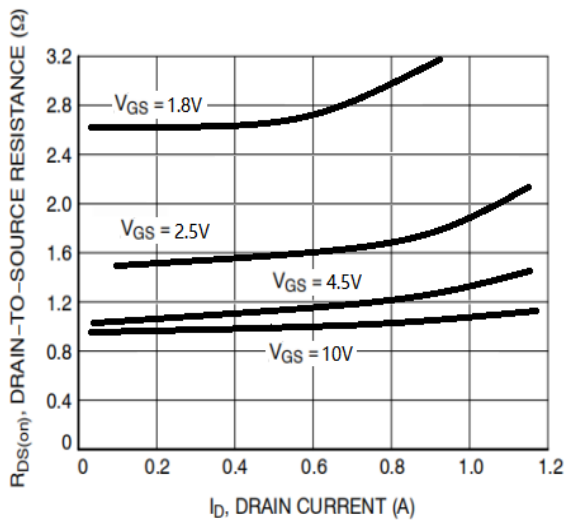


Figure 3. On-Resistance vs. Drain Current and Temperature

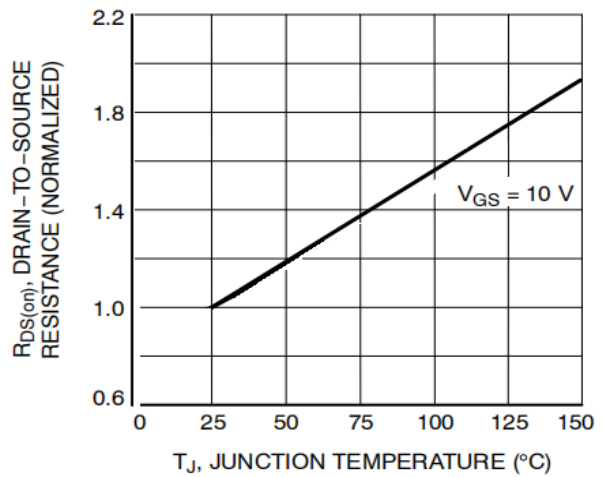


Figure 4 On-Resistance Variation with Temperature

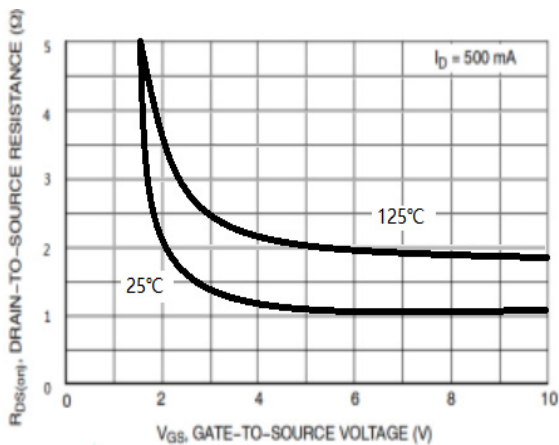


Figure 5. On-Resistance vs. Gate-to-Source Voltage

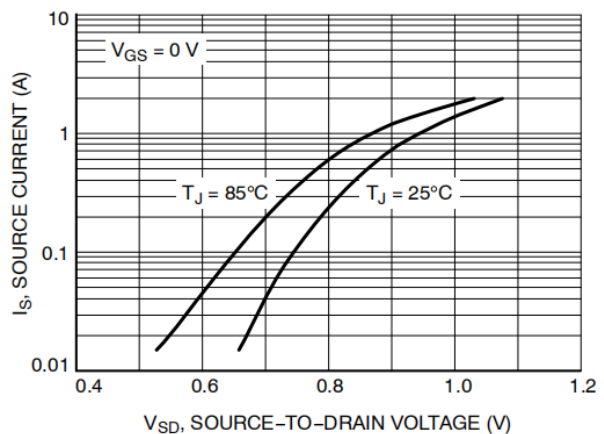


Figure 6 Diode Forward Voltage vs. Current

电参数曲线图 / Electrical Characteristic Curve

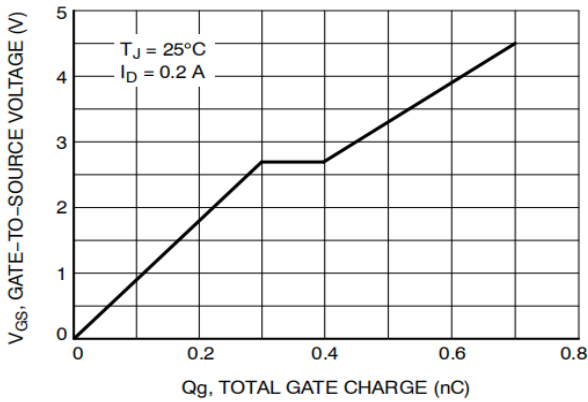


Figure 7. Gate-to-Source and Drain-to-Source Voltage vs. Total Charge

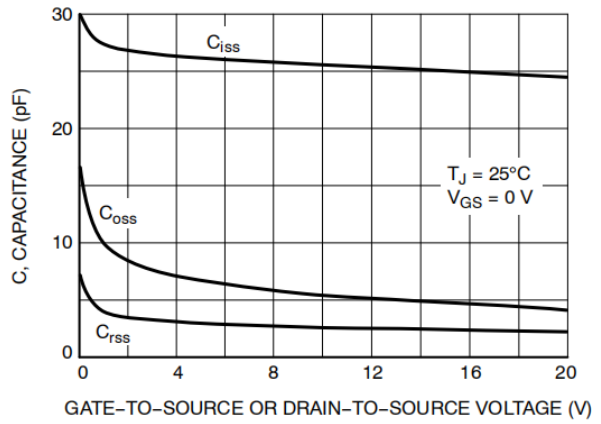


Figure 8. Capacitance Variation

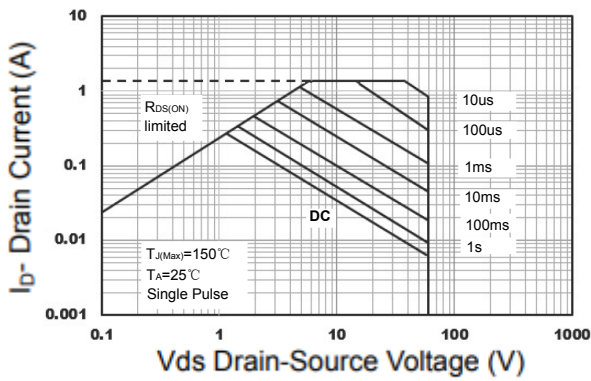


Figure 9 : Safe Operation Area

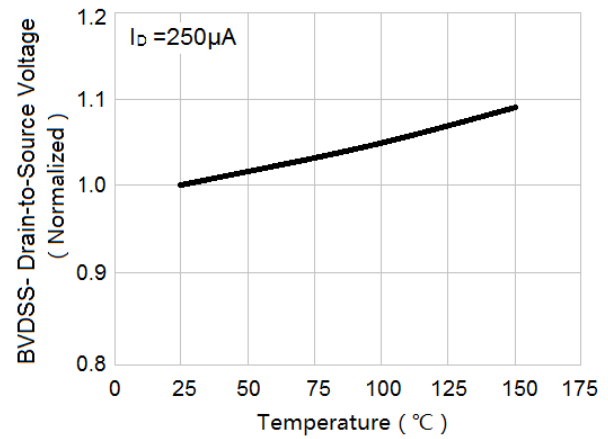


Figure 10 : Breakdown Voltage vs. Temperature

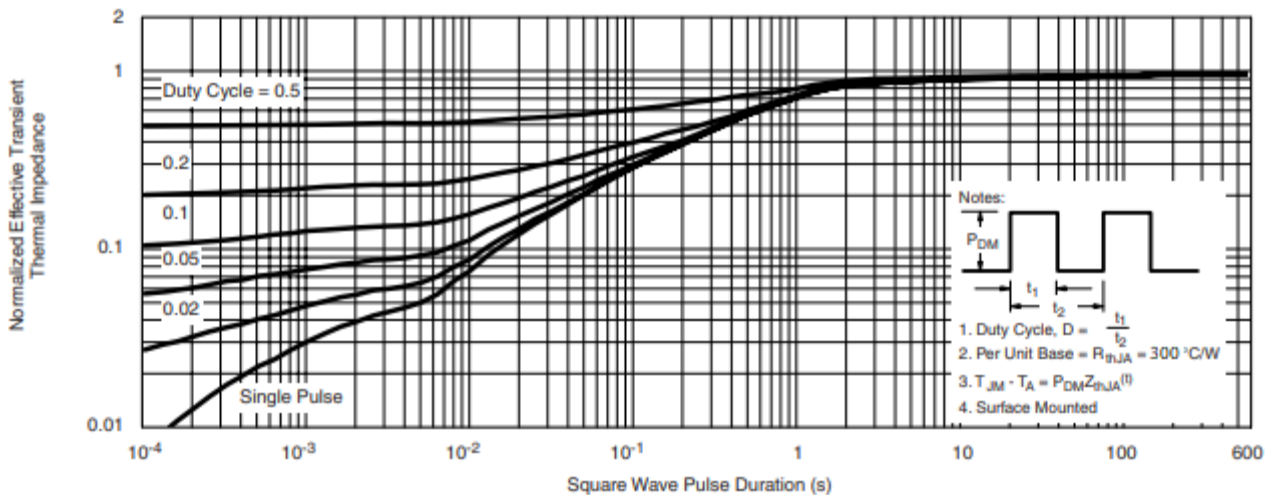
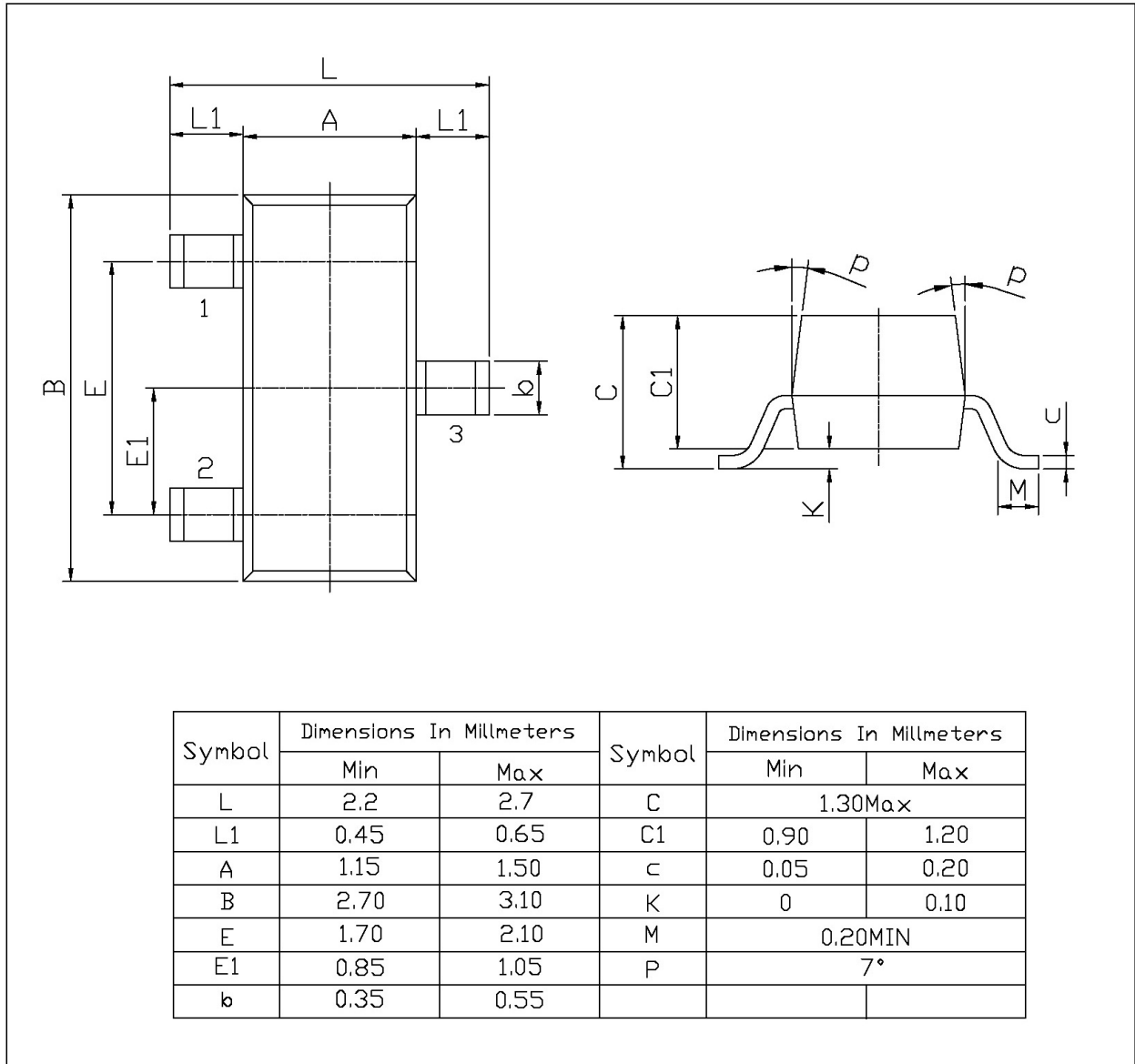


Figure 11 : Normalized Thermal Transient Impedance, Junction-to-Ambient

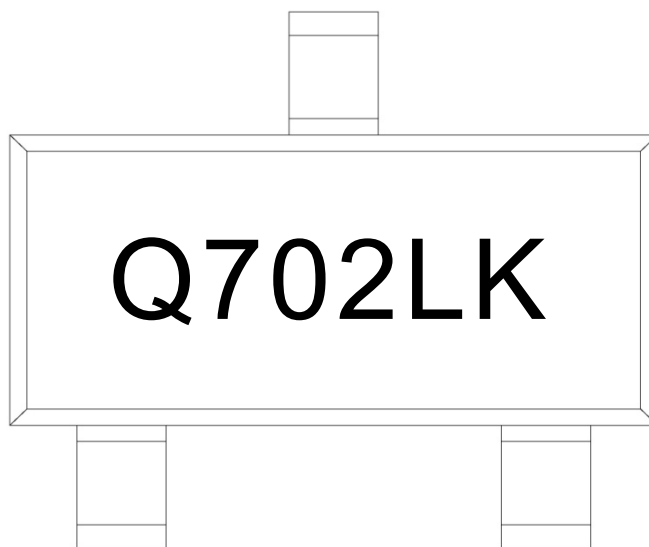
外形尺寸图 / Package Dimensions

SOT-23

单位: mm



印章说明 / Marking Instructions



说明：

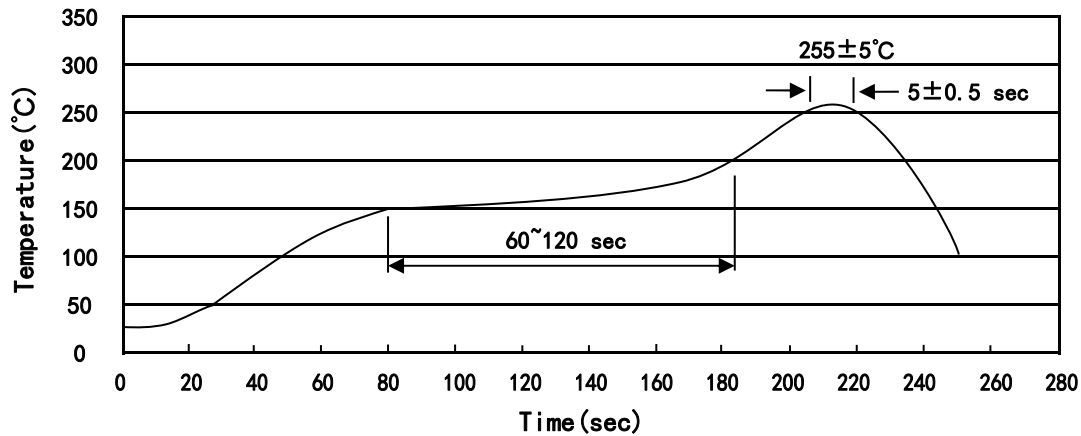
Q： 为汽车无卤产品标识

702LK： 为型号代码

Note:

Q: Automobile halogen-free product Code

702LK: Product Type Code

回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)


说明：

- 1、预热温度 150~200°C，时间 60~120sec;
- 2、峰值温度 255±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2~10°C/sec.

Note:

- 1.Preheating:150~200°C, Time:60~120sec.
- 2.Peak Temp.:255±5°C, Duration:5±0.5sec.
- 3.Cooling Speed: 2~10°C/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

包装规格 / Packaging SPEC.

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOT-23	3,000	10	30,000	6	180,000	7" ×8	180×120×180	390×385×205

使用说明 / Notices